

ABSTRACT

There has been no appropriate means to test connections between two integrated circuits packaged in a single semiconductor package. This invention offers a test method on internal connections in a semiconductor package housing a first integrated circuit and a
5 second integrated circuit connected with each other, including applying a test signal to a first pin of the semiconductor package, applying the test signal from the first pin to the first integrated circuit, applying a first signal generated in the first integrated circuit from the test signal to the second integrated circuit, applying a second signal generated in the second integrated circuit from the first signal back to the first integrated circuit, leading a
10 third signal generated in the first integrated circuit from the second signal out of the semiconductor package through a second pin of the semiconductor package and confirming connections between the first integrated circuit and the second integrated circuit by verifying the third signal led out of the semiconductor package.